**Dual N-Ch MOSFET** 

### **General Description**

The WST3392 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3392 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

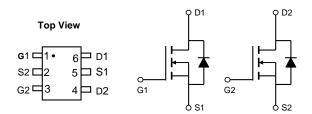
### **Product Summery**

BVDSS	RDSON	ID
30V	40mΩ	3.7A

### **Applications**

- Power management in portable and battery operated products
- One cell battery pack protection

### **SOT-23-6L Pin Configuration**



# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	3.7	Α	
I <sub>D</sub> @T <sub>C</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	3.0	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	Α	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.15	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$	
TJ	Operating Junction Temperature Range -55 to 150		°C	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		110	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		80	°C/W



**Dual N-Ch MOSFET** 

# Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.028		V/°C
		V <sub>GS</sub> =10V , I <sub>D</sub> =3.5A		40	50	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}$ =6V , $I_D$ =2A		45	65	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =2A		58	73	
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/   -250A	1.0	1.5	2.0	0 V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-3.21		mV/℃
	Drain-Source Leakage Current	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>		V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =5A		12		S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		4	6	Ω
Qg	Total Gate Charge (4.5V)			4.05	5	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =10V , I <sub>D</sub> =3.5A		0.55	0.8	nC
Q <sub>gd</sub>	Gate-Drain Charge			1.0	1.8	
T <sub>d(on)</sub>	Turn-On Delay Time			4.5		
T <sub>r</sub>	Rise Time	1 1 0 A D 1 0 0		1.5		ns
T <sub>d(off)</sub>	Turn-Off Delay Time			18.5		
T <sub>f</sub>	Fall Time			15.5		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		170	210	
C <sub>oss</sub>	Output Capacitance			35	45	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			23	30	

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V =V =0V Force Current			1.5	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			3.5	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{SD}$ =3.5A , $T_{J}$ =25 $^{\circ}$ C			1.0	V
t <sub>rr</sub>	Reverse Recovery Time			7.5		nS
Q <sub>rr</sub>	Reverse Recovery Charge	lF=3.5A,dI/dt=100A/μs , T <sub>J</sub> =25℃		2.5		nC

### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150 ℃ junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.





### **Typical Characteristics**

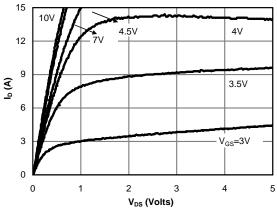


Fig 1: On-Region Characteristics (Note E)

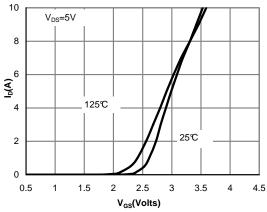


Figure 2: Transfer Characteristics (Note E)

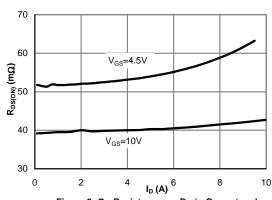


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

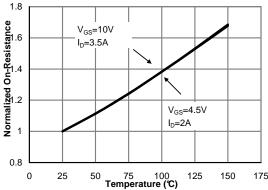


Figure 4: On-Resistance vs. Junction Temperature (Note E)

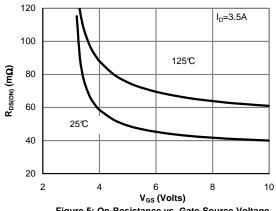


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

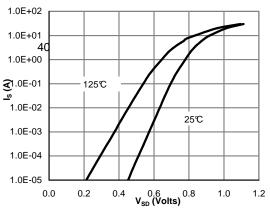


Figure 6: Body-Diode Characteristics (Note E)



## **Typical Characteristics**

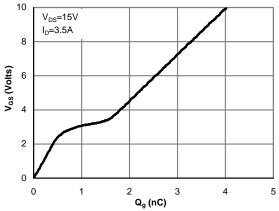


Figure 7: Gate-Charge Characteristics

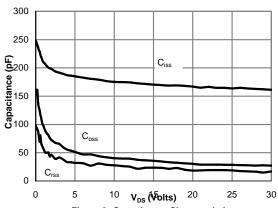


Figure 8: Capacitance Characteristics

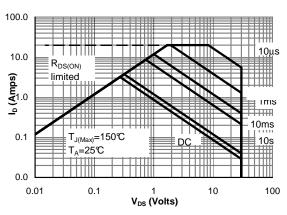
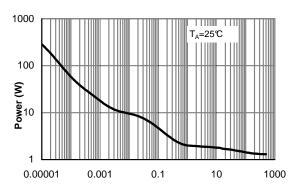


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)



Pulse Width (s)
Figure 10: Single Pulse Power Rating
Junction-to-Ambient (Note F)

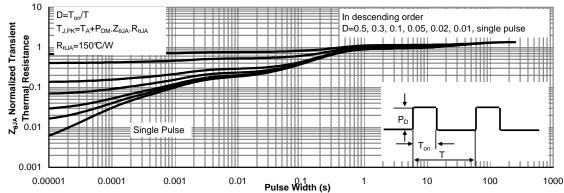


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



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